

Senior Software Engineer II

| Expertise | Finite Element Analysis (FEA), High-Performance Computing (HPC), Computational Mechanics, Cloud Computing, Machine Learning, Additive Manufacturing, Computer-Aided Engineering (CAE), Deep Learning, Artificial Neural Networks (ANN), Mechanical Simulation, Message Passing Interface (MPI), CUDA, GPU, OpenMP, Structural Analysis, Software Development, Composites, International Management, Project Management, Operations Management, Operations Research, Optimization, Hard Disk Drives, Biomechanics, Soft Tissue, User Experience Design |
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| Education | Doctor of Philosophy (Mechanical Engineering), 2007 University of Pittsburgh, Pittsburgh, PA, USA |
| | Master of Business Administration, 2012 University of California at Irvine, Irvine, CA, USA |

Professional Experience

| 2022 – Present | ITASCA Minneapolis Senior Software Engineer II |
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| 2020 – 2021 | Rescale, San Francisco, California Senior Application Engineer / Solutions Architect |
| 2019 | Raylytyc, Leipzig, Germany Softwareentwinkler |
| 2014 – 2019 | Autodesk, San Francisco, California and State College, Pennsylvania User Experience Designer and Research Engineer |
| 2011 – 2014 | NEi Software, Westminster, California Senior Application Engineer and International Channel Manager |
| 2007 – 2009 | Western Digital, San Jose, California Principal Engineer |
| 2003 – 2007 | Ansys, Inc., Canonsburg, Pennsylvania Quality Assurance Engineer |

Project Experience

Deep Learning in Healthcare: Led the development of AI-based tools for medical image registration, segmentation and analysis.

High-Performance Computing in Additive Manufacturing Simulation: Developed an MPI version of a commercial additive manufacturing simulation code (Autodesk Netfabb).

Mesh-independent Cracking (MIC): Developed MIC finite elements that allow simulation of crack propagation (delamination and transverse matrix cracks) in composite materials independent of finite element mesh.